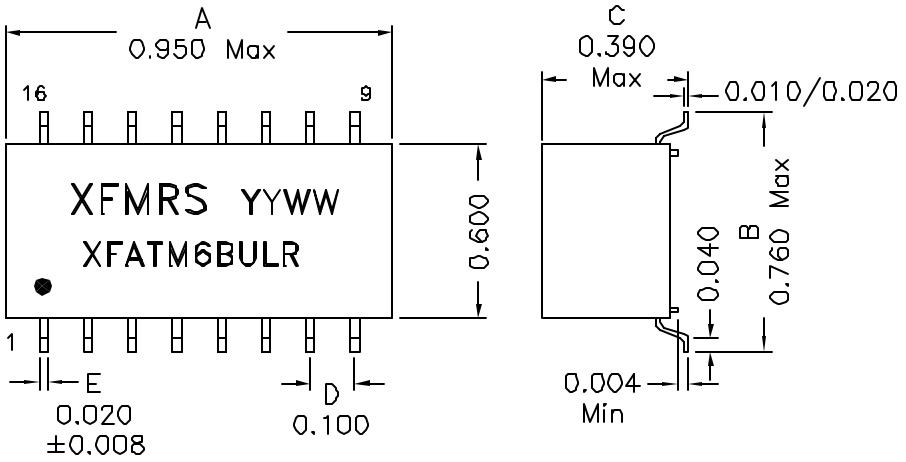
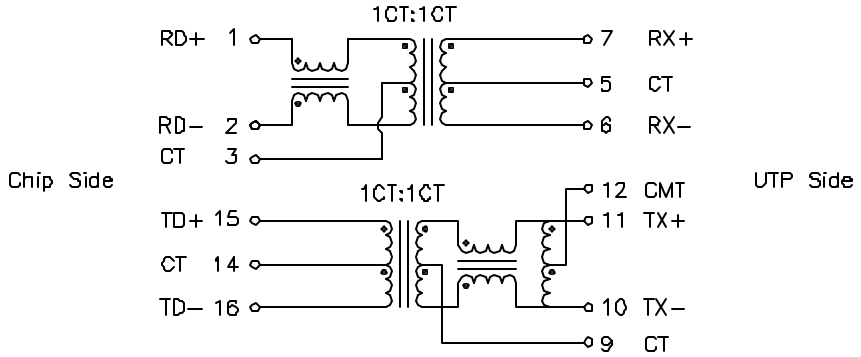
1. Dimensions:

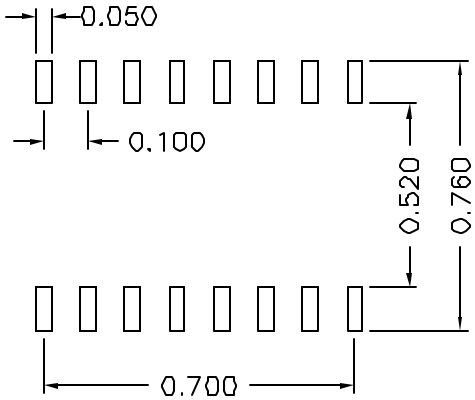


2. Schematic:



3. Electrical Specifications: @25°C

UTP Impedance: 100 OHMS
Turns Ratio: TX: 1CT:1CT (±2%) RX: 1CT:1CT (±2%)
Isolation Voltage: 3000 Vrms (CHIP to UTP)
UTP Side OCL: 350uH Minimum @100KHz, 100mV 8mADC
UTP Side Q: 18 Minimum @100KHz, 100mV
Rise Time (10–90%): 2.5nS Typical
Insertion Loss (1M–80MHz): 1.2dB Maximum
Return Loss (1–30MHz): –18dB Min
(30–60MHz): –12dB Min
(60–100MHz): –10dB Min
DCMR (1–30MHz): –35dB Min
(30–100MHz): –30dB Min
(100–150MHz): –25dB Min
Crosstalk (1–60MHz): –40dB Minimum
(60–100MHz): –38dB Minimum



SUGGESTED PCB LAYOUT

Notes:

1. Solderability: Leads shall meet MIL–STD–202G, Method 208H for solderability.
2. Flammability: UL94V–0
3. ASTM oxygen Index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from –40°C to +85°C
6. Storage Temperature Range: –55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component
11. Designed to meet UL60950 for Reinforced Insulation.

DOC. REV A/1

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XFMRS Inc www.XFMRS.com	Title: SMD Xfmr for 10/100Mb Reinforced Insulaiton		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in Inch	P/N: XFATM6BULR		REV. A
	DWN.	Mei Chen	Mar–27–09
	CHK.	YK Liao	Mar–27–09
SHEET 1 OF 1	APP.	Joe Huff	Mar–27–09